

RENESAS

HVL397CM

Variable Capacitance Diode for VCO

REJ03G0014-0100Z

Rev.1.00

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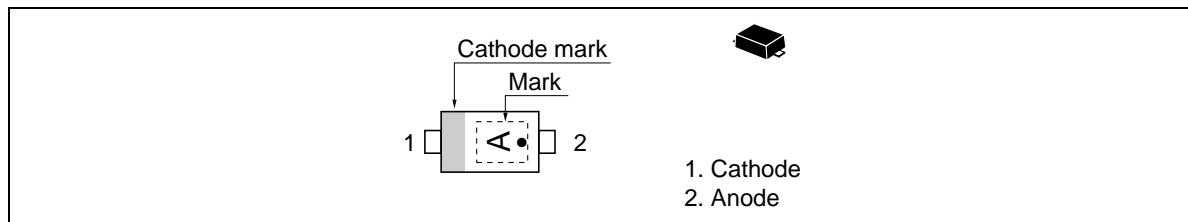
Features

- High capacitance ratio. ($n = 2.9$ min)
- Thin Extremely small Flat Package (TEFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVL397CM	A	TEFP

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V _R	15	V
Junction temperature	T _j	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	I _{R1}	—	—	10	nA	V _R = 10 V
	I _{R2}	—	—	50		V _R = 10 V, Ta = 60°C
Capacitance	C ₁	27.0	—	28.5	pF	V _R = 1 V, f = 1 MHz
	C ₂	18.0	—	20.0		V _R = 2 V, f = 1 MHz
	C ₄	6.80	—	8.50		V _R = 4 V, f = 1 MHz
Capacitance ratio	n ₁	1.3	—	—	—	C ₁ / C ₂
	n ₂	2.9	—	—	—	C ₁ / C ₄
Series resistance	r _s	—	—	1.2	Ω	V _R = 1 V, f = 470 MHz

Notes:

1. Please do not use the soldering iron due to avoid high stress to the TEFP package.
2. The material of lead is exposed for cutting plane. Therefore, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic

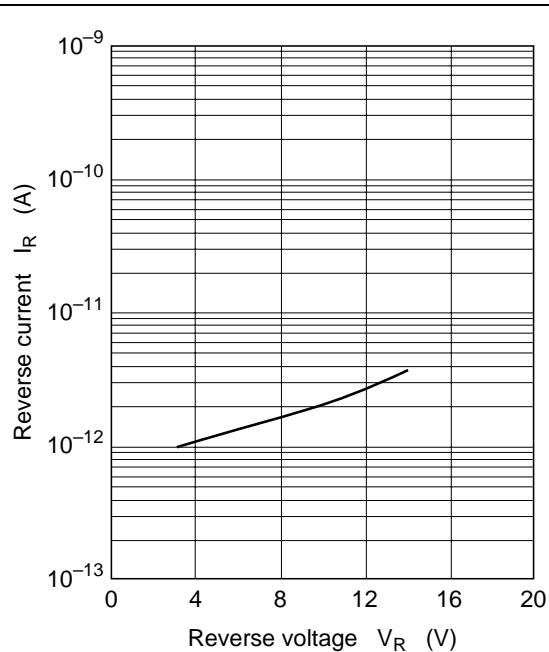


Fig.1 Reverse current vs. Reverse voltage

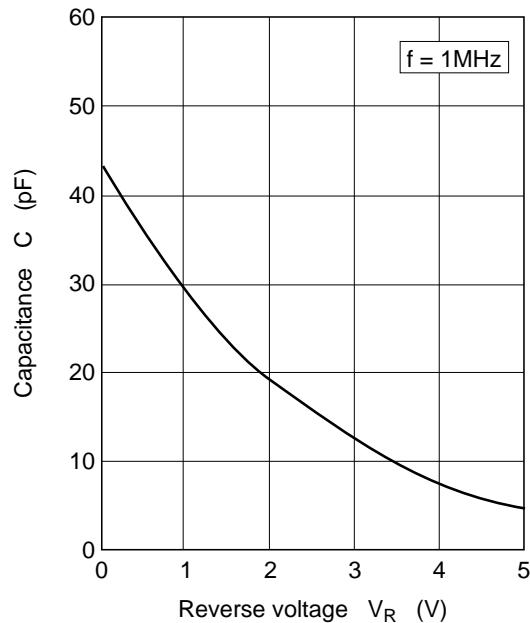


Fig.2 Capacitance vs. Reverse voltage

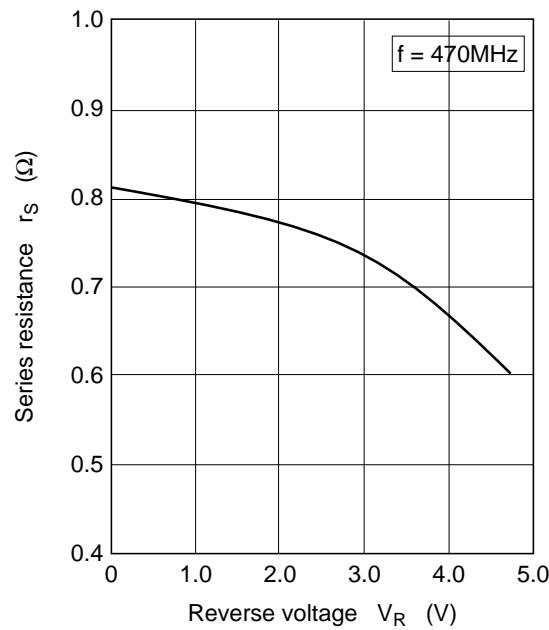


Fig.3 Series resistance vs. Reverse voltage

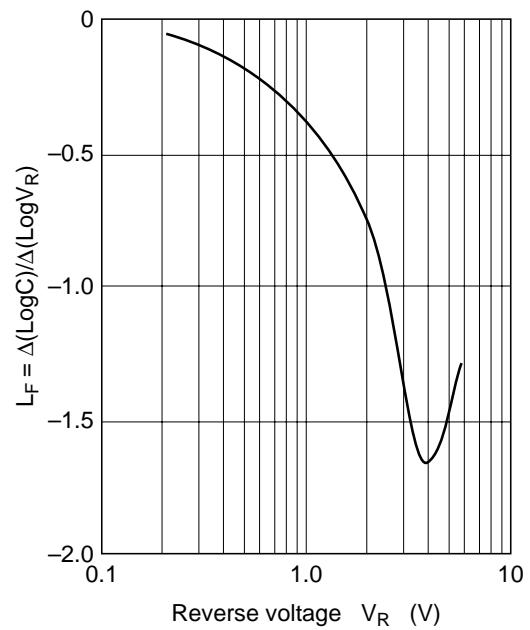
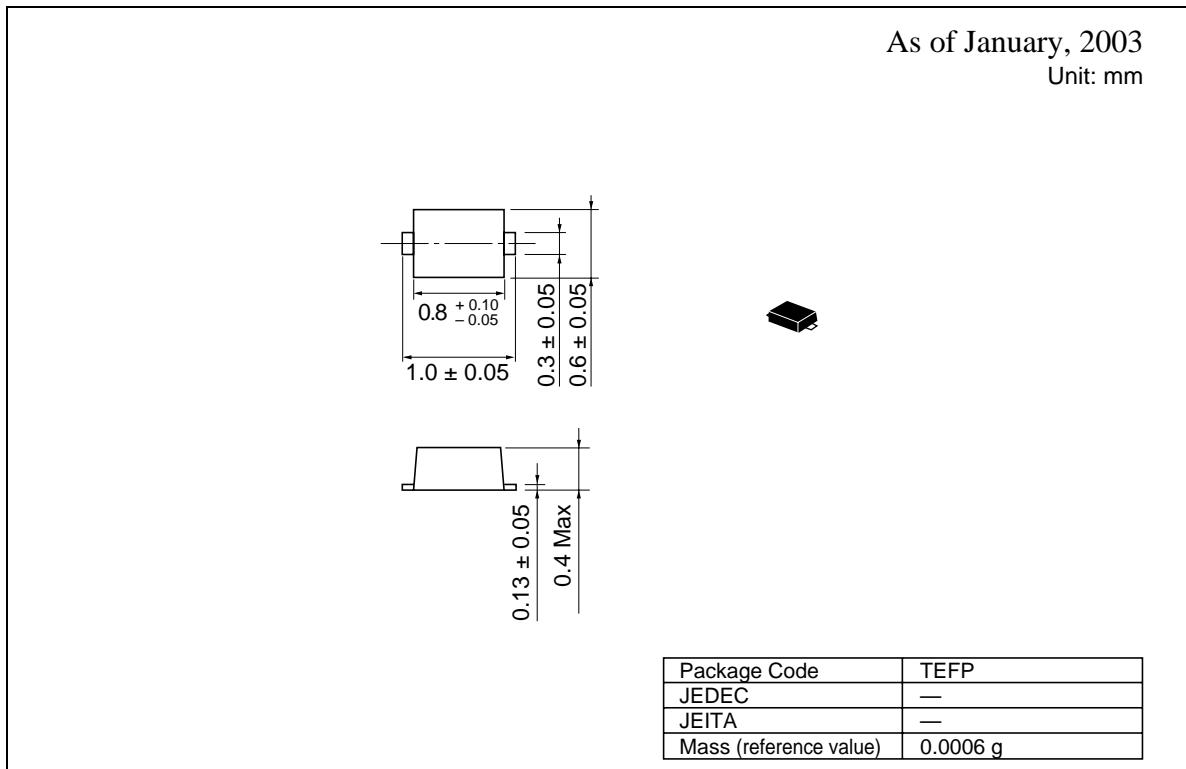


Fig.4 Linearity factor vs. Reverse voltage

Package Dimensions



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